Product Specification

Product:	Conductive Silver Paste
Part Number:	01M-3405

Application Scope :
This product is suitable for PTC resistor electrodes.

Usage Conditions :

Substrate	PTC pottery and porcelain
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (adjust time based on actual leveling conditions).
Drying	Bake in a ventilation oven at 100-150°C for 10-15 minutes (the test temperature should not exceed 300°C; the baking time may be adjusted based on actual conditions).
Firing Condition	The sintering temperature is 600°C (recommended value) and the sintering time is 10 minutes. The slurry has a broad sintering temperature range, adjustable between 480-750°C as needed, with the peak temperature maintained for 10 minutes.
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic		Standard	Test Method And Conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	80-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10 rpm, with viscosity adjustable to 25±1°C according to user requirements.

2. Characteristics After Curing :

Under the 1-sintering condition, the film thickness is 8-12 μm.
Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test Method And Conditions
3	Resistivity	≤5mΩ/□	Test pattern 0.6mm×60mm
4	Adhesion Strength		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	≥43.2N	
	Ageing Adhesion	≥23.6N	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product shall be stored in a sealed container at an ambient temperature of 5-25°C, with a shelf life of 1 year from the date of shipment.

Packaging Method :

Standard packaging, 1000g/can; samples are available in 200g small can packaging.

Compound Name	Mass Percentage (%)
Silver	70—75
Glass and Inorganic Additives	2-5
Aluminum Oxide	＜0.03
Silicon Dioxide	＜0.04
Zinc Oxide	＜1.5
Boron Oxide	＜0.06
Bismuth Oxide	＜1.0
Barium Oxide	＜0.02
Copper Oxide	＜0.8
Ethyl Cellulose	＜2.5
Diethylene Glycol Butyl Ether Acetate	＜20